

WHAT IS CLAIMED IS:

1. A heat-peelable pressure-sensitive adhesive sheet comprising a substrate and formed on at least one side thereof a heat-expandable pressure-sensitive adhesive layer containing heat-expandable microspheres, wherein the heat-expandable pressure-sensitive adhesive layer has a surface resistivity of $10^{12} \Omega/\square$ or lower.

2. The heat-peelable pressure-sensitive adhesive sheet of claim 1, wherein the heat-expandable pressure-sensitive adhesive layer before heating has a center line average surface roughness of 2 μm or less.

3. The heat-peelable pressure-sensitive adhesive sheet of claim 1, wherein the heat-expandable pressure-sensitive adhesive layer before heating has a maximum surface roughness of 5 μm or less.

4. The heat-peelable pressure-sensitive adhesive sheet of claim 1, which has a rubber-like organic elastic layer interposed between the substrate and the heat-expandable pressure-sensitive adhesive layer.

5. The heat-peelable pressure-sensitive adhesive sheet of claim 4, wherein the rubber-like organic elastic layer comprises a pressure-sensitive adhesive material.